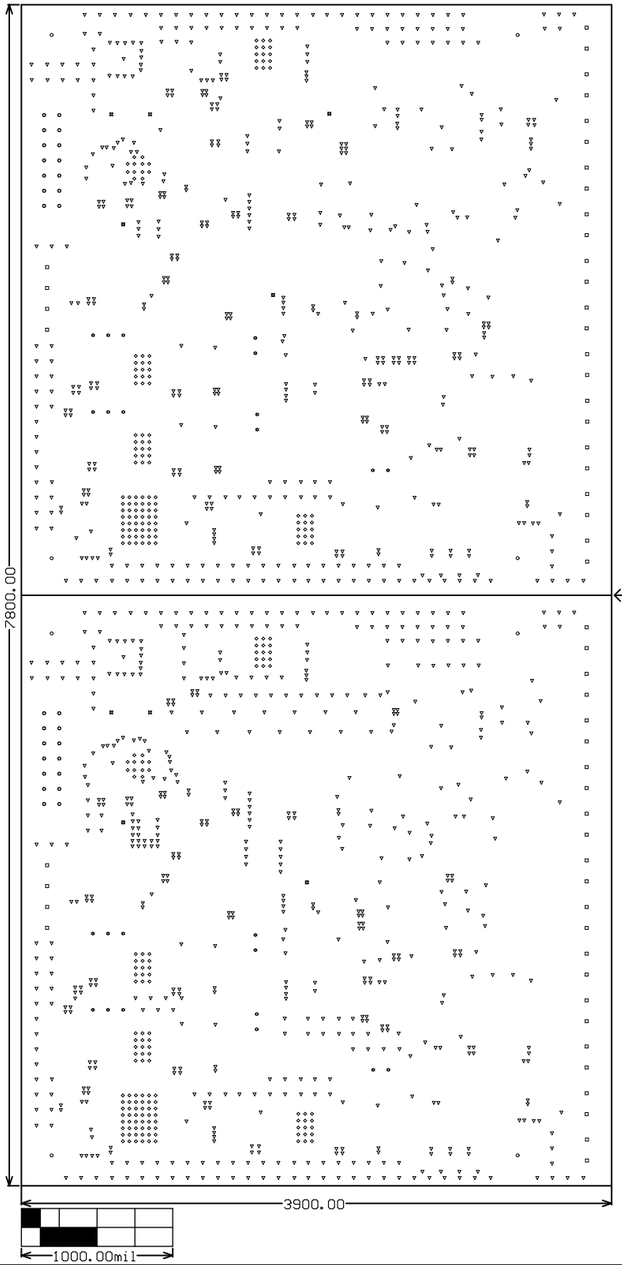

← NOTE A

NOTE A :

V_Score is required at the mentioned location in between the two boards.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 1	PP-006	5.00mil	4.1	
2	GND 1		1.38mil		
	Dielectric 3	PP-006	6.00mil	4.1	
3	Signal		1.38mil		
	Dielectric1	FR-4	31.79mil	4.8	
4	Power		1.38mil		
	Dielectric 4	PP-006	6.00mil	4.1	
5	GND 2		1.38mil		
	Dielectric 2	PP-006	5.00mil	4.1	
6	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
◇	240	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
▽	1161	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⌬	28	37.00mil (0.940mm)	PTH	Round	Top Layer - Bottom Layer	
◙	5	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
✡	24	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
□	56	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	4	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
○	8	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	1526 Total					

DESIGN INFORMATION

MIN. TRACK WIDTH: 6.5 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 20 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL,HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL(1.6mm)+/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS--> [ ]1 [X]2 [ ]3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[X] OUTER 7.5 MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE,XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: Versatile Satellite Health Monitoring and Control Platform
DESIGNED FOR: Public Release
FILE NAME: PCB_Project_2_PCB.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-010197	REV: E1	SVN REV: Not in version control
LAYER NAME = [illegible]sions	TID #: TIDA-010197		
PLOT NAME = Fabrication Drawing	GENERATED : 7/14/2021 10:58:00 AM	TEXAS INSTRUMENTS	

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ENGINEER: Wenchau Albert Lo	LAYOUT BY: Krypton Solutions
SCALE: 1.00	ALTIUM DESIGNER VERSION: 21.5.1.32